DOCUMENT: M20099 **REV LETTER: G** PAGE NO: 1 OF 1 REV DATE: 2019-11-25 PART NUMBER:

Polymer **PTC Devices**

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Surface mount fuses

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Features

- Surface mount devices
- Withstanding high interrupt voltage
- Lead-free and compliant with the European Union RoHS Directive 2011/65/EU



| Product Dime | nsions (mm) | | | | | |
|---------------|-------------|-----------|-----------------|-----------------|-----------------|--|
| Dert number | A B | | С | D | E | |
| Part number - | Тур. | Тур. | Тур. | Тур. | Тур. | |
| LM130F | 9.10±0.30 | 3.15±0.25 | 7.00 ± 0.40 | 0.30 ± 0.05 | 3.80 ± 0.30 | |







* Terminal materials: Tin-plated brass. * Lead-free devices are available,

the right logo is lead-free mark of wayon.

Electrical Characteristics

| Part | Ι _Η | Ι _Τ | Max. Time-to-trip | | V _{max} | I _{max} | Pd _{typ} | R _{min} | R _{max} | R _{1max} |
|--------|----------------|----------------|-------------------|---------|------------------|------------------|-------------------|-------------------------|-------------------------|-------------------|
| number | (A) | (A) | Current(A) | Time(s) | (V) | (A) | (W) | (Ω) | (Ω) | (Ω) |
| LM130F | 0.13 | 0.26 | 1.00 | 2.5 | 250 | 3.0 | 3.0 | 6.5 | 12.0 | 20.0 |

I_H=Hold current: maximum current at which the device will not trip at 25 $^{\circ}$ still air.

I_T=Trip current: minimum current at which the device will always trip at 25 $^{\circ}$ C still air.

Max. Time-to-trip =Maximum time to trip(s) at assigned current. V_{max} =Maximum voltage device can withstand without damage at rated current. I_{max} =Maximum fault current device can withstand without damage at rated voltage.

Pdtvp=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

 R_{min} =Maximum device resistance at 25 °C prior to tripping. R_{max} =Maximum device resistance at 25 °C prior to tripping. R_{1max} =Maximum device resistance at 25 °C one hour post trip.

Thermal Derating Chart-IH(A)

| LM130F | Maximum ambient operating temperatures($^{\circ}$ C) | | | | | | | | | |
|------------------|---|-------|-------|-------|-------|-------|-------|-------|-------|--|
| LIVITSUF | -40 | -20 | 0 | 25 | 40 | 50 | 60 | 70 | 85 | |
| Hold Current (A) | 0.208 | 0.182 | 0.156 | 0.130 | 0.104 | 0.091 | 0.078 | 0.065 | 0.045 | |
| Trip Current (A) | 0.416 | 0.364 | 0.312 | 0.260 | 0.208 | 0.182 | 0.156 | 0.130 | 0.090 | |

Solder Reflow Recommendations



| Solder Pad Layouts | | | | | | | |
|--------------------|------|------|------|--|--|--|--|
| Dent much an | Α | В | С | | | | |
| Part number | (mm) | (mm) | (mm) | | | | |
| LM130F | 4.6 | 1.8 | 6.1 | | | | |

Recommended reflow methods: IR, Vapor phase oven, hot air oven.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requiremen

Package Information Bulk: 1000pcs per bag. Tape & Reel: 1500pcs per reel.